

The LHCb Silicon Tracker Project

Johan Blouw, for the Silicon Tracker Group

max-planck institute für kernphysik

introduction

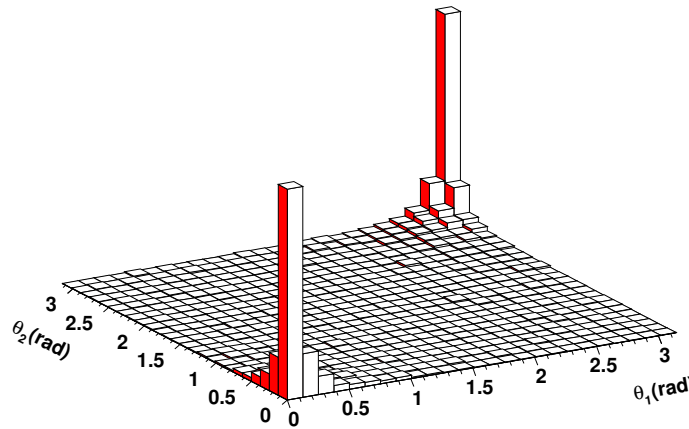
- The LHCb Spectrometer
- Why Use Silicon?
- Trigger Tracker
- Inner Tracker
- Readout Chip
- Testbeam Results
- Outlook

Why LHCb?

- CP-violation used to explain matter over anti-matter dominance in universe.
- But, current CP-violation data insufficient to explain matter abundance
- new experiments needed to measure CP-violation in B_s system
- Hence LHCb...

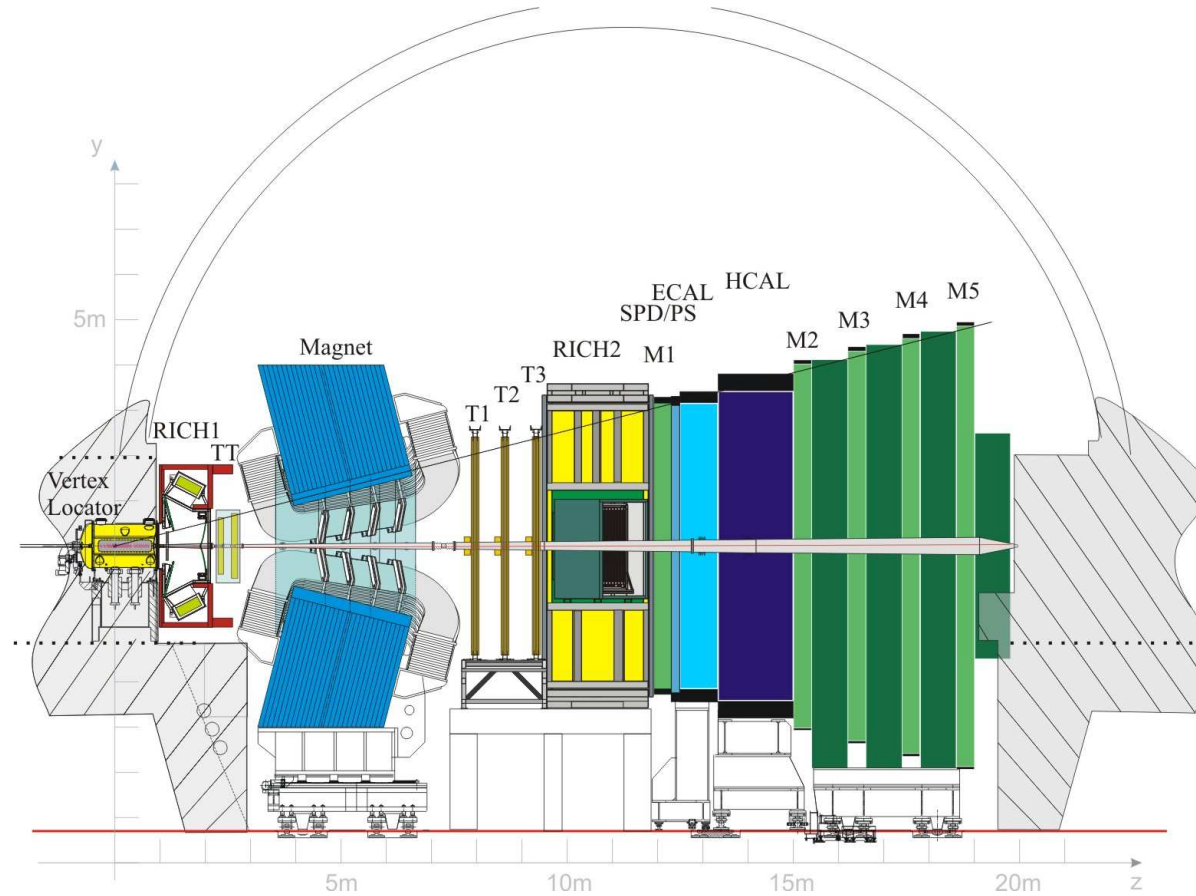
Why LHCb?

- At LHC, $b\bar{b}$ pairs produced at forward and backward angles \rightarrow



- construct a forward-angle spectrometer

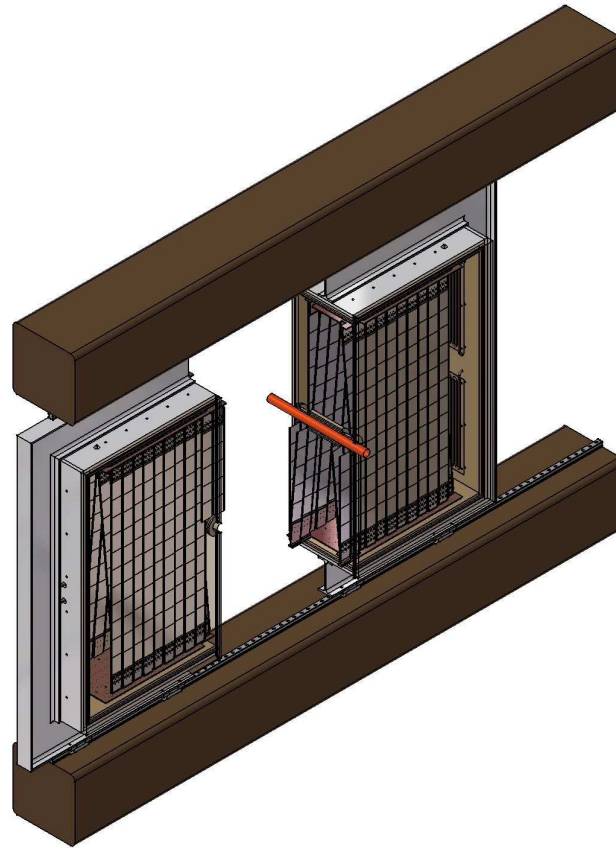
Why LHCb?



Why use silicon?

- At high luminosity ($1.5 \times 10^{32} \text{cm}^{-2} \text{s}^{-1}$), high trigger rate (1 MHz) \rightarrow good event rejection needed.
- Use tracking station (Trigger Tracker) to measure P_T of tracks and apply in L1 trigger.
- high particle density ($5 \times 10^5 \text{cm}^{-2} \text{s}^{-1}$) around beam-pipe \rightarrow
- employ silicon-strip technology for inner part of spectrometer

Trigger Tracker



- cover large area with silicon (total of 8.3 m^2)
- located in fringe-field in front of dipole magnet

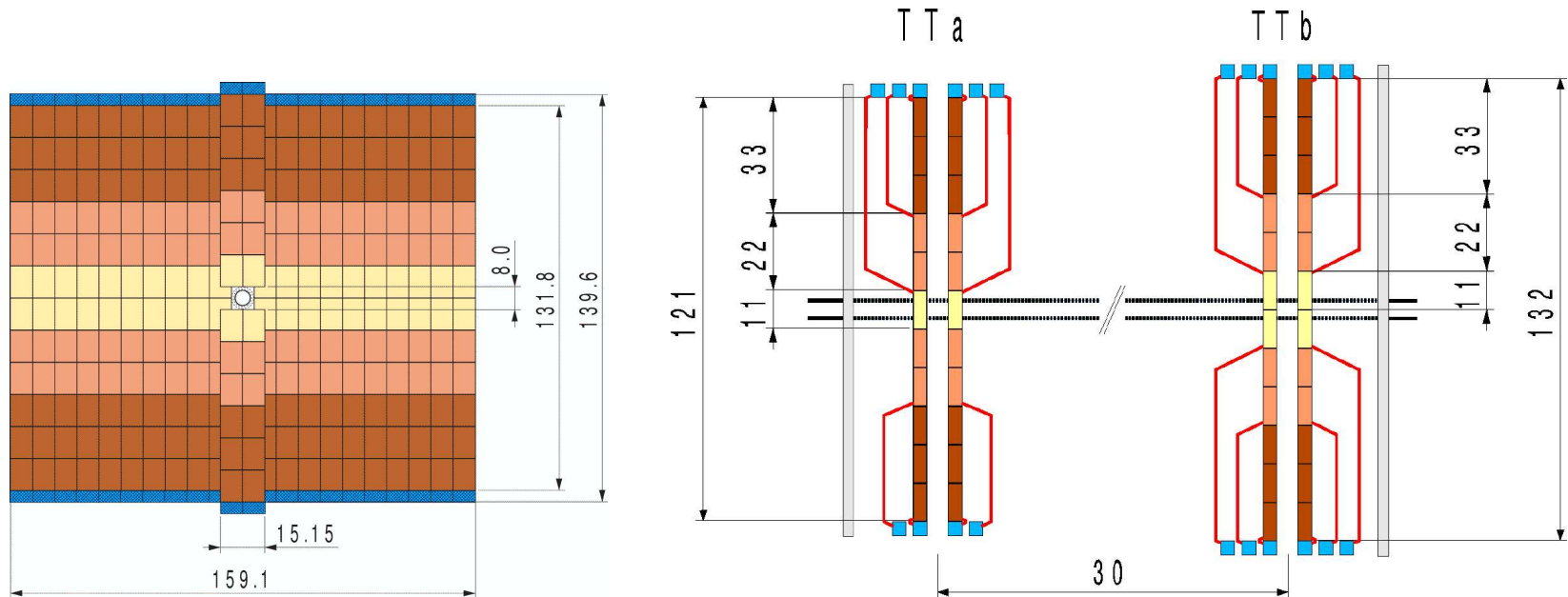
Trigger Tracker

- need many sensors glued together to cover acceptance
- front-end needs to be outside acceptance →
- signal transport may be a problem



- use Kapton cables to connect lower sensors to front-end

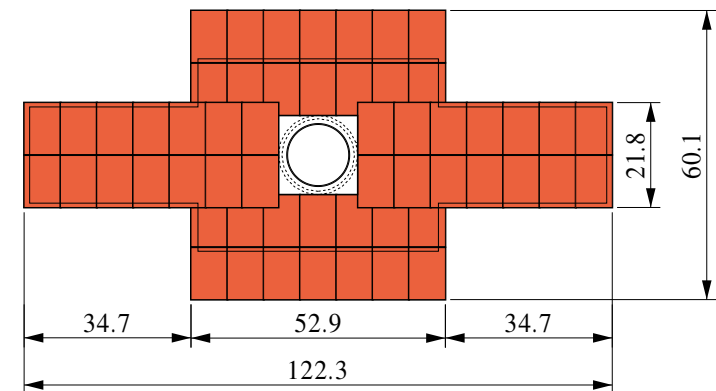
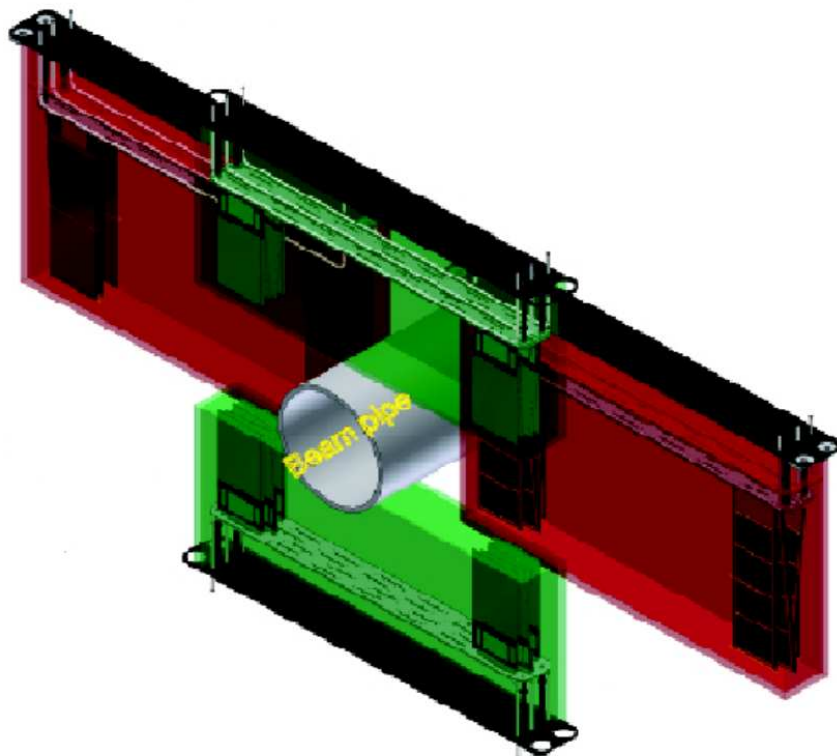
Trigger Tracker



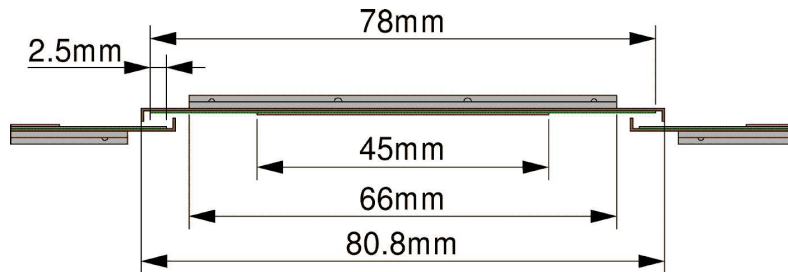
- two stations with each two planes in an (x, x') and $(u, v 5^\circ \text{ stereo-angle})$ configuration
- connect inner substrates with flexible Kapton cable to read-out frontends

Inner Tracker

- located in proximity of beampipe behind magnet
- 1.3% areal size, 20% of tracks
- two station, four boxes of four layers each



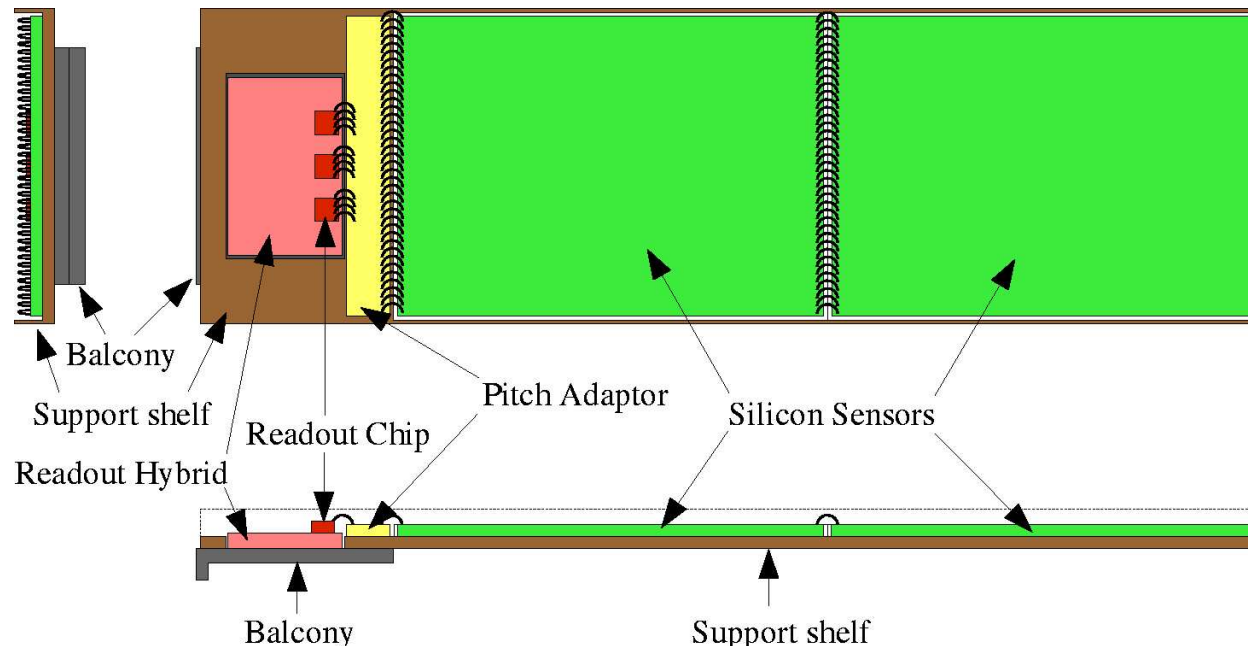
Inner Tracker



- overlap between layers
- 197 μm pitch
- $110 \times 78 \text{ mm}^2$ size sensors
- operating temperature 5°C
- close to 100% hit finding efficiency
- 1-and 2-sensor ladders

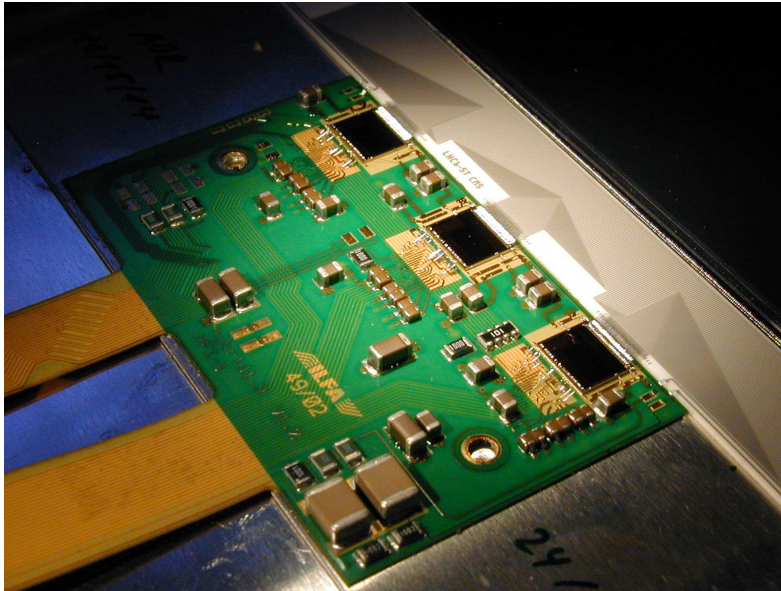
Sensor Design

- different sensor types used in test beam
- various geometrical designs (pitch, width, thickness)



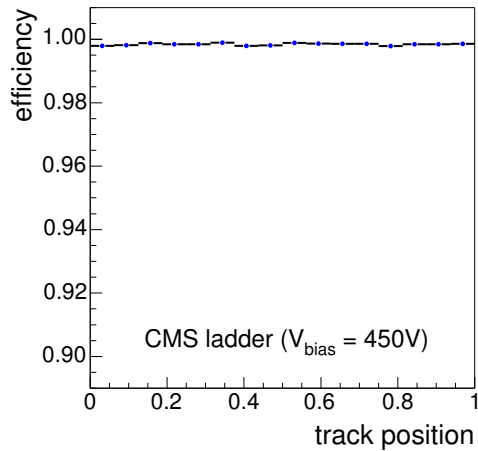
- study signal-over-noise behaviour for
- different substrate thicknesses

Front-end

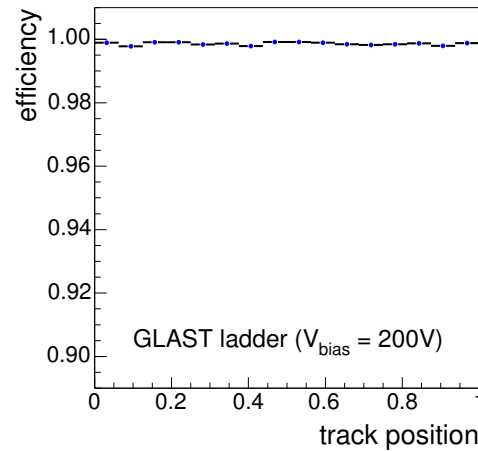


- Beetle chip developed by Asic lab in Heidelberg
- 64 channel, fast readout (40 MHz)
- three Beetle front-end chips per hybrid
- study pulsheshapes on different loads
- signal remainder
- tracking efficiency

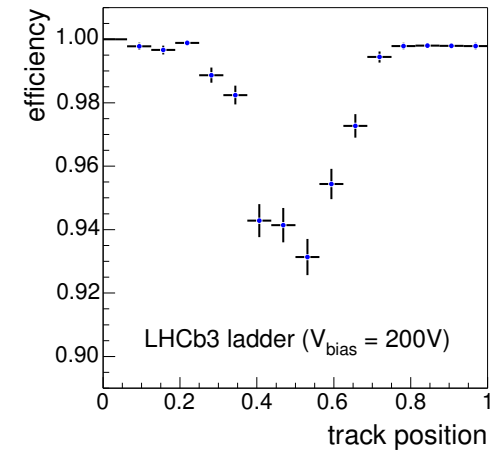
Test Beam Results



500 μm thick
180 μm pitch

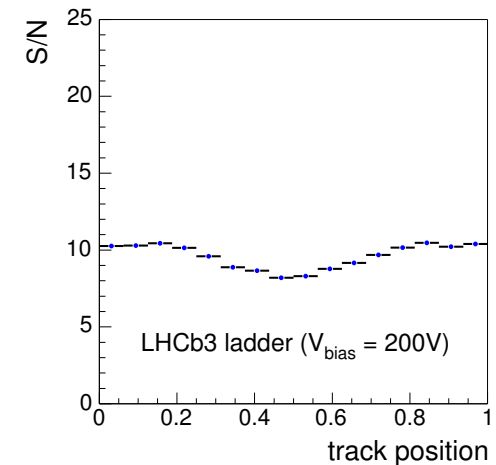
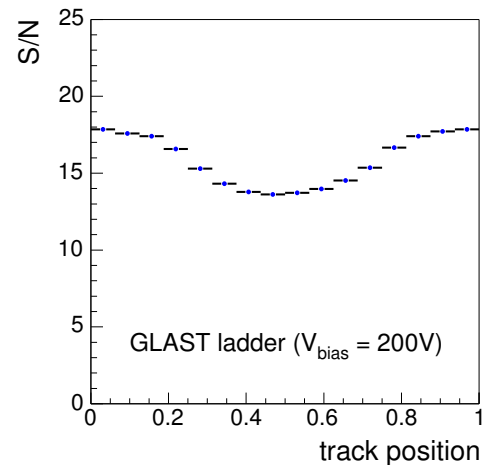
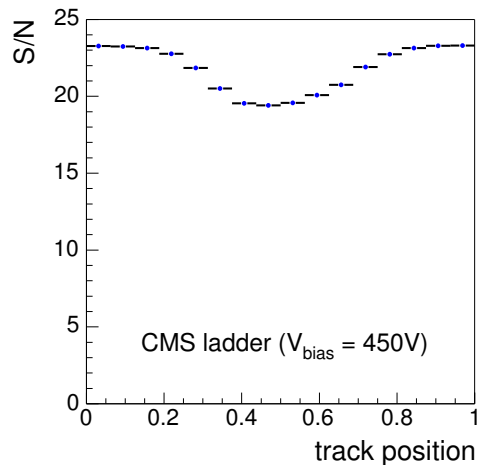


410 μm thick
228 μm pitch



320 μm thick
198 μm pitch

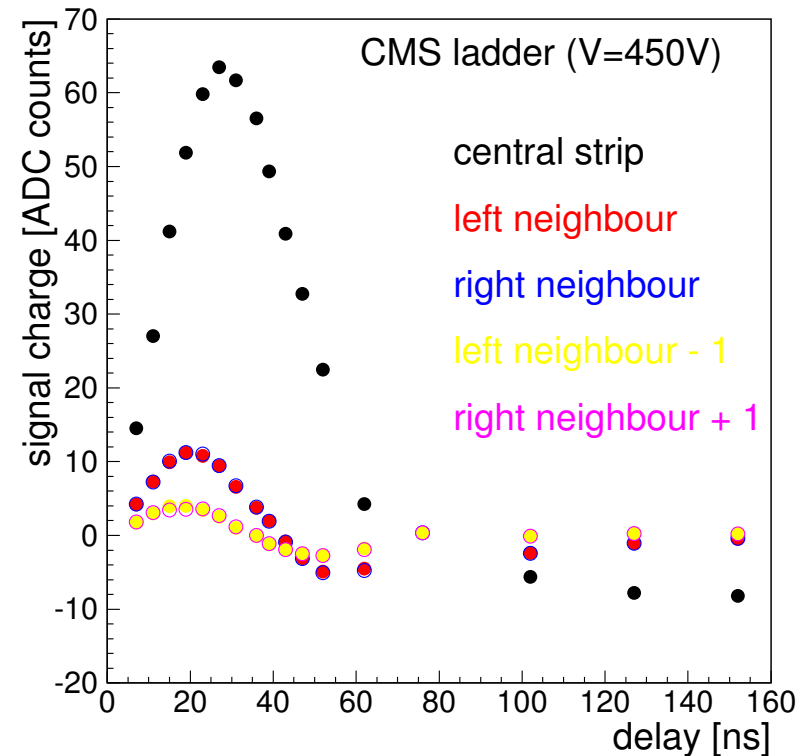
Test Beam Results



- signal drop in between two strips due to charge loss
- impact on efficiency for $S/N < 10$
- signal drop largest for thinner substrates

Test Beam Results

- fast read-out: signal remainder after 25 ns < 50% of peaking time
- mirror charge arrives quicker
- Beetle chip fullfills LHC requirements
- sufficient tuning possible to accomodate various load capacities



Outlook

- minimal substrate thickness: $400 \mu\text{m}$
- no adverse effect on tracking and physics performance:
- large pitch: $200 \mu\text{m}$
- long strips: 10 – 30 cm
- fast read-out: $O(25 \text{ ns})$

